

**IN THE CLAIMS:**

Claims 3-4 and 7-11 have been withdrawn.

Please amend claims 1 and 5 as follows:

**LISTING OF CURRENT CLAIMS**

Claim 1. (Currently Amended) An IC package with an implanted heat-dissipation fin, comprising:

an encapsulant having a PCB side and an opposing open side;

a chip inside the encapsulant; and

a heat-dissipation fin ~~implanted in the encapsulant and having a portion thereof extending outside the open side.~~ having an upper portion and a lower portion, the lower portion having a predetermined amount of the encapsulant located on a top thereof and the upper portion extending outwardly above the opposing open side of the encapsulant.

Claim 2. (Original) The IC package with an implanted heat-dissipation fin according to claim 1, wherein said heat-dissipation fin contacts directly with said chip.

Claim 3. (Withdrawn) The IC package with an implanted heat-dissipation fin according to claim 1, wherein said heat-dissipation fin spaces from said chip by a predetermined spacing.

Claim 4. (Withdrawn) The IC package with an implanted heat-dissipation fin according to claim 1, wherein said portion of said heat-dissipation fin further has at least a hookup point.

Claim 5. (Currently Amended) A method for implanting a heat-dissipation fin while packing an IC chip, comprising:

~~having positioning a chip encapsulated inside an encapsulant at in~~ a melted state;

before the encapsulant ~~being is~~ cured, implanting a heat-dissipation fin into ~~in the encapsulant at a predetermined position above the chip and with a portion of the heat-dissipation fin left outside the encapsulant; and~~ position, in the predetermined position a lower portion of the heat-dissipation fin having a predetermined amount of the encapsulant located on a top thereof and an upper portion of the heat-dissipation fin extending outwardly above the opposing open side of the encapsulant; and

~~holding in position the encapsulant and the heat-dissipation fin till the encapsulant being~~ in the predetermined position until the encapsulant is cured.

Claim 6. (Original) The method for implanting a heat-dissipation fin while packing an IC chip according to claim 5, wherein said predetermined position is a solid contact state.

Claim 7. (Withdrawn) The method for implanting a heat-dissipation fin while packing an IC chip according to claim 5, wherein said predetermined position is a position with a predetermined spacing.

Claim 8. (Withdrawn) The IC package with an implanted heat-dissipation fin according to claim 1, wherein said heat-dissipation fin comprises a bottom portion having at least one opening for said encapsulant filling within the opening of the bottom portion.

Claim 9. (Withdrawn) The IC package with an implanted heat-dissipation fin according to claim 8, wherein said heat-dissipation fin further comprises a plurality of upper portion contacting said bottom portion and extending to outsides of said open side.

Claim 10. (Withdrawn) The method for implanting a heat-dissipation fin while packing an IC chip according to claim 5, wherein said heat-dissipation fin comprises a bottom portion having at least one opening for said encapsulant filling within the opening of the bottom portion.

Claim 11. (Withdrawn) The method for implanting a heat-dissipation fin while packing an IC chip according to claim 10, wherein said heat-dissipation fin further comprises a plurality of upper portion contacting said bottom portion and extending to outsides of said open side.